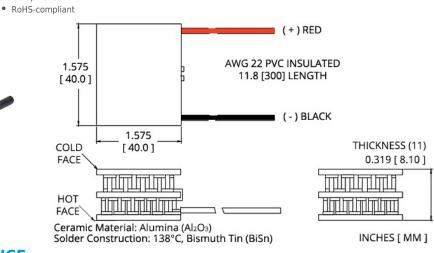
#### Multistage MS Series Thermoelectric Cooler

The MS2-192-14-20-15-25-11-W8 multistage thermoelectric cooler is able to reach colder temperatures than single stage thermoelectric coolers. It has a maximum Qc of 24.3 Watts when  $\Delta T=0$  and a maximum  $\Delta T$  of 91  $^{\circ}C$  at Qc = 0.

#### **Features**

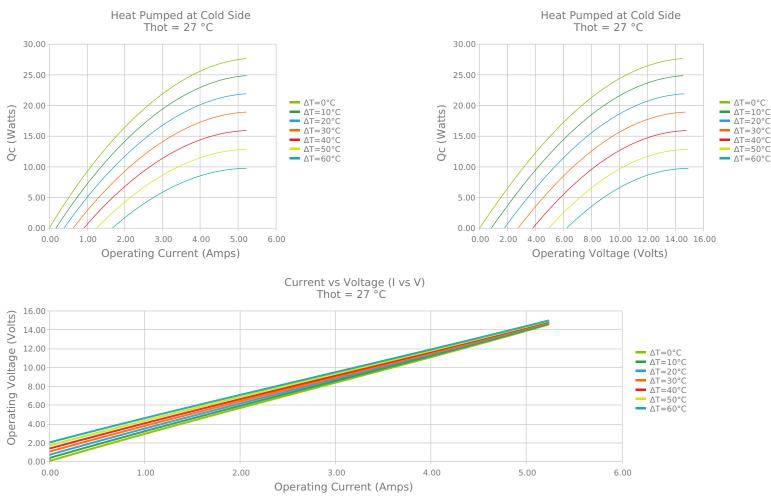
- High temperature differential
- Precise temperature control
- Reliable solid-state operation
- Environmentally-friendly DC operation

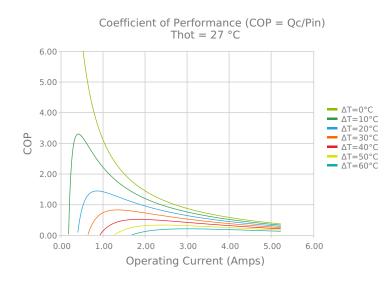
- **Applications**
- Thermoelectric Cooling for CMOS Sensors
- Heads-Up Displays, Imaging Sensors

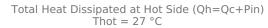


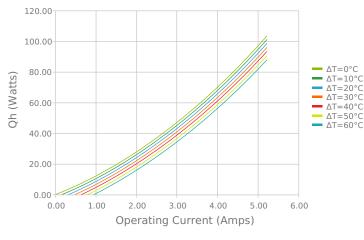
# **ELECTRICAL AND THERMAL PERFORMANCE**

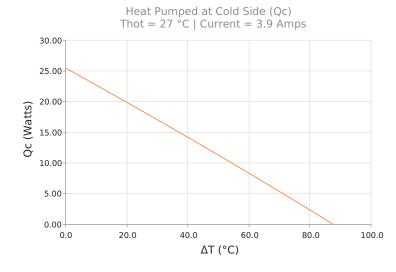
For maximum performance, be sure to orient the CONTROL side of the TEC against the application to be managed and the HEATSINK side against the heat sink or other heat rejection method. The CONTROL side is always opposite the side with lead attachments. Lead attachment is a passive heat loss and less impactful if located on the side that attaches to the heat exchanger.

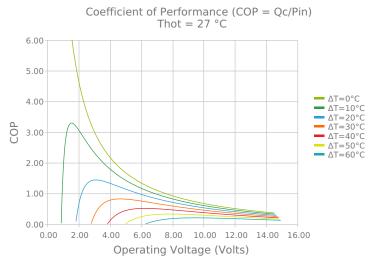


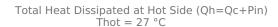


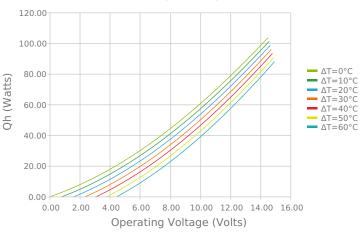




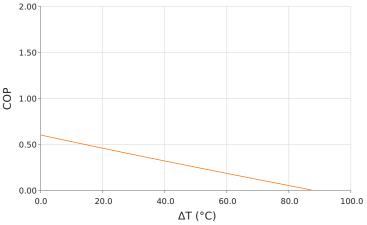








Coefficient of Performance (COP = Qc/Pin) Thot = 27 °C | Current = 3.9 Amps



#### **SPECIFICATIONS\***

Hot Side Temperature	27.0 °C
$Qcmax (\Delta T = 0)$	24.3 Watts
$\Delta T max (Qc = 0)$	91.0 °C
lmax (I @ ΔTmax)	5.1 Amps
Vmax (V @ ΔTmax)	14.7 Volts
Module Resistance	2.88 Ohms
Max Operating Temperature	80 °C
Weight	46.0 gram(s)

\* Specifications reflect thermoelectric coefficients updated March 2020

## **FINISHING OPTIONS**

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length
11	8.100 ±0.203 mm 0.319 ± 0.008 in	0.025 mm / 0.203 mm 0.001 in / 0.008 in	Lapped	Lapped	199.9 mm 7.87 in

## **SEALING OPTIONS**

Suffix	Sealant	Color	Temp Range	Description	
	None			No sealing specified	

## **NOTES**

- 1. Max operating temperature: 80°C
- 2. Do not exceed Imax or Vmax when operating module
- 3. Reference assembly guidelines for recommended installation
- 4. Solder tinning also available on metallized ceramics

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